



Material Content Data Sheet



Sales Product Name		BSP772T		Issued		22. January 2018		
MA#		MA000975768						
Package		PG-DSO-8-24		Weight*		83.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.222	3.86	3.86	38569	38569
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8585	
wire	non noble metal	copper	7440-50-8	29.121	34.86	35.77	348595	357716
	noble metal	gold	7440-57-5	0.410	0.49	0.49	4905	4905
	encapsulation	organic material	carbon black	1333-86-4	0.095	0.11		1139
plastics	plastics	epoxy resin	-	4.378	5.24		52409	
	inorganic material	silicondioxide	60676-86-0	43.115	51.62	56.97	516115	569663
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9742	9742
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7784	7784
glue	plastics	epoxy resin	-	0.170	0.20		2034	
	noble metal	silver	7440-22-4	0.801	0.96	1.16	9587	11621
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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